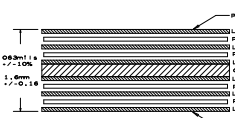
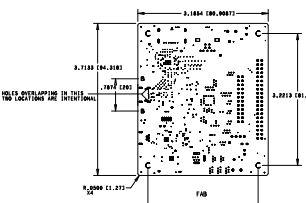
REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
1	INITIAL RELEASE	04/11/16	RAJA
2	ALPHA RELEASE	01/12/16	RAJA
3	BETA RELEASE	22/12/16	RAJA
4	PRODUCTION RELEASE	20/01/16	RAJA
5	PRODUCTION RELEASE	01/04/16	RAJA
6	PRODUCTION RELEASE	23/10/16	RAJA



NOTE: 6 MIL & MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED
NOTE: 6 MIL 10.3 MIL SPACING TRACES ON LAYER 4 DIFFERENTIAL IMPEDANCE CONTROLLED TO 100 OHMS +/- 10% TESTED
NOTE; 6 MIL & MIL SPACING TRACES ON LAYER 6 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED



DRILL CHARTS "TOP" to BOTTOM

ALL UNITS ARE IN MILLIMETERS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
+	0.3937	+0.0762/-0.0762	PLATED	253
-	0.254	+0.0/-0.254	PLATED	20
*	0.254	+0.0762/-0.0762	PLATED	98
+	0.381	+0.0762/-0.0762	PLATED	169
#	0.4064	+0.0762/-0.0762	PLATED	10
+	0.7112	+0.0762/-0.0762	PLATED	3
+	0.7762	+0.0762/-0.0762	PLATED	3
+	0.9982	+0.0762/-0.0762	PLATED	4
+	1.016	+0.0762/-0.0762	PLATED	87
H	1.0	+0.0762/-0.0762	PLATED	4
B	2.2	+0.0762/-0.0762	PLATED	2
CI	2.3962	+0.0762/-0.0762	PLATED	2
*	3.2	+0.0762/-0.0762	PLATED	2
A	3.4	+0.0000/-0.0508	NON-PLATED	1
C	3.179	+0.0000/-0.0508	NON-PLATED	4
#	1.2446±0.1	+0.0762/-0.0762	PLATED	2
B	1.745.01	+0.0762/-0.0762	PLATED	2
##	1.9986±0.1008	+0.0762/-0.0762	PLATED	2
##	1.0996±0.101	+0.0762/-0.0762	PLATED	2
##	2.01±.1	+0.0762/-0.0762	PLATED	2
B	2.245.01	+0.0762/-0.0762	PLATED	2
###	3.119±0.089	+0.0762/-0.0762	PLATED	1
B	3.119±0.089	+0.0762/-0.0762	PLATED	1
###	3.0001±.149	+0.0762/-0.0762	PLATED	1
W	0.0±0.5	+0.0000/-0.0508	NON-PLATED	1

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED.
2. MATERIAL;
   A. IS410 OR EQUIVALENT, MATERIAL HUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM.
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION.
3. DRILLING;
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING;
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING;
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE, LOGO AND RoHS COMPILANT SYMBOL IN SILKSCREEN ON SECONDARY SIDE.
6. FINAL FABRICATION;
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR eBLUEee
7. FINISH;
   A. SHALL BE ELECTROLESS NIKEL & IMMERSION GOLD(ENIG).
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY. FLAMBILITY RATING (94-V0).
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WARP OR TWIST SHALL NOT EXCEED .007 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GUARANTEE WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.
12. ENSURE ALL THE VIA HOLES ARE FILLED WITH SOLDER MASK TO ENSURE GOOD QUALITY OF SILK SCREEN PRINT.
13. CARE MUST BE TAKEN TO AVOID OVER ETCHING OF COPPER ON PADS.

UNLESS OTHERWISE SPECIFIED
DIMENSIONS ARE IN INCHES
TOLERANCES ON: ANGLES +/- 2°
2 PL DECIMALS +/- .010
3 PL DECIMALS +/- .005
THIRD ANGLE PROJECTION

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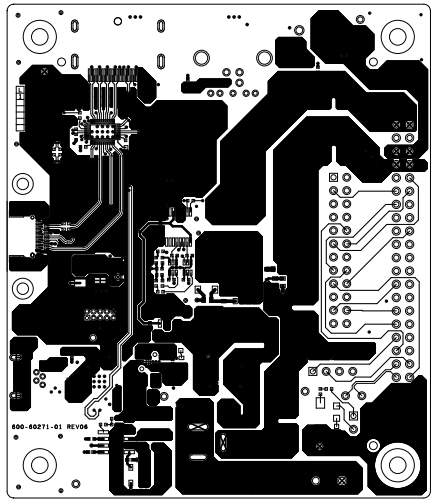
SIGNATURES		DATE
DRAWN :	HUSAIN	25/10/16
CHECKED :	RAJA	25/10/16
ENGR :	RAGO	25/10/16
ISSUED		

CYPRESS SEMICONDUCTOR
198 CHAMPION COURT
SAN JOSE, CA 95134
(408) 943-2600

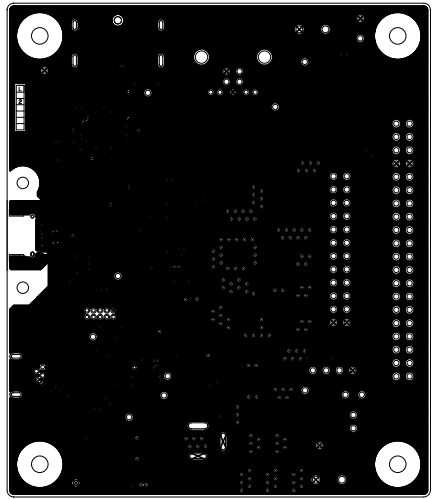
FABRICATION DRAWING
CCG EVK BASE BOARD

SIZE	FSCM NO	DWG NO	REV
C		610-60275-01	06

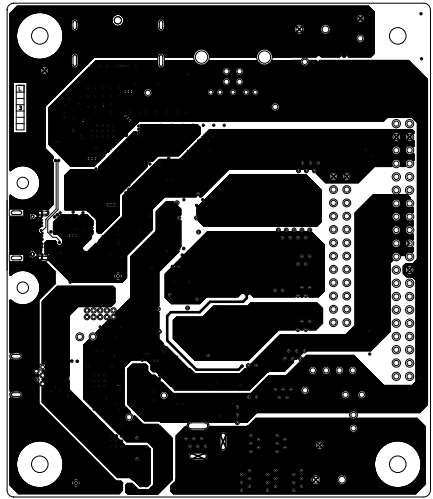
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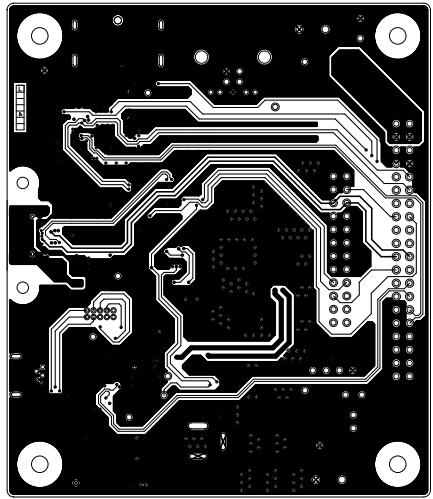
600-60271-01 REV06 PRIMARY SIDE



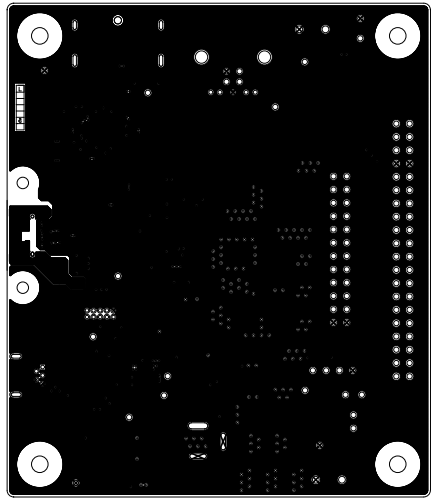
600-60271-01 REV06 GROUND1 LAYER



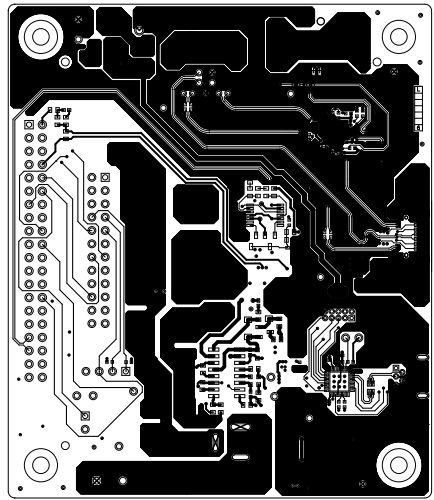
600-60271-01 REV06 POWER1 LAYER



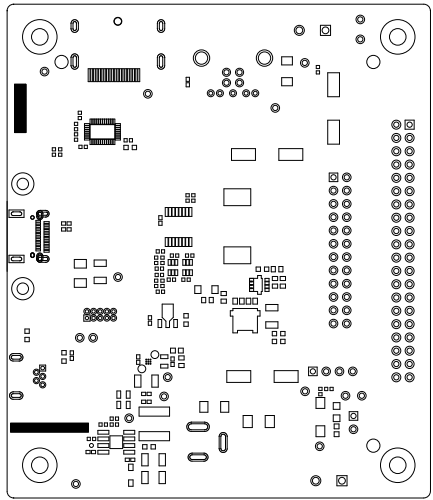
600-60271-01 REV06 SIGNAL1 LAYER



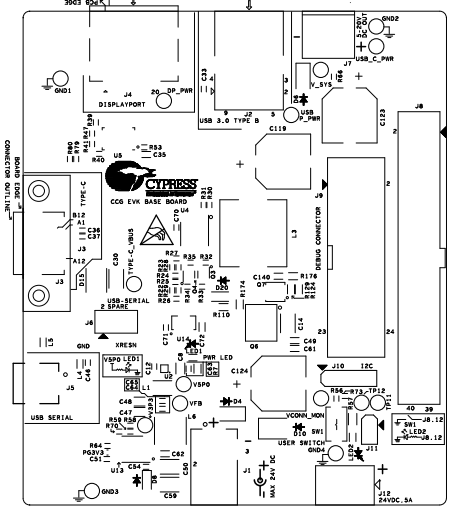
600-60271-01 REV06 GROUND2 LAYER



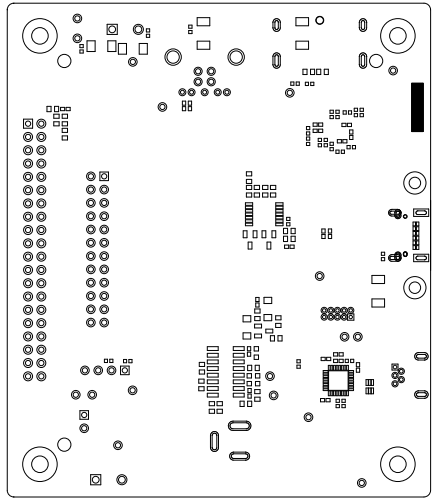
600-60271-01 REV06 SECONDARY SIDE



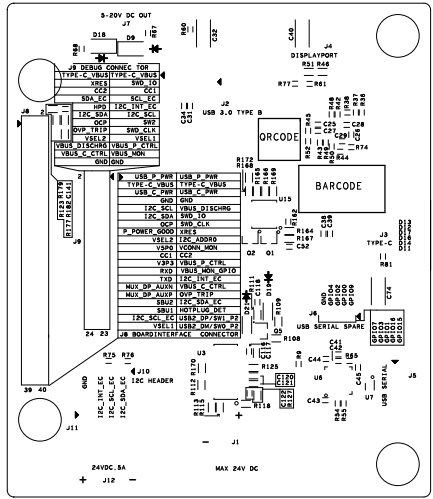
600-60271-01 REV06 PRIMARY SOLDERMASK



600-60271-01 REV06 PRIMARY SILKSCREEN



600-60271-01 REV06 SECONDARY SOLDER MASK



600-60271-01 REV06 SECONDARY SILKSCREEN